

Title (en)

ELECTROPLATING BATH FOR ELECTROCHEMICAL DEPOSITION OF A CU-SN-ZN-PD ALLOY, METHOD FOR ELECTROCHEMICAL DEPOSITION OF SAID ALLOY, SUBSTRATE COMPRISING SAID ALLOY AND USES OF THE SUBSTRATE

Title (de)

GALVANIKBAD ZUR ELEKTROCHEMISCHEN ABSCHIEDUNG EINER CU-SN-ZN-PD-LEGIERUNG, VERFAHREN ZUR ELEKTROCHEMISCHEN ABSCHIEDUNG VON DIESER LEGIERUNG, SUBSTRAT MIT DIESER LEGIERUNG UND VERWENDUNG DES SUBSTRATS

Title (fr)

BAIN D'ÉLECTRODÉPOSITION POUR LE DÉPÔT ÉLECTROCHIMIQUE D'UN ALLIAGE CU-SN-ZN-PD, PROCÉDÉ DE DÉPÔT ÉLECTROCHIMIQUE DE CET ALLIAGE, SUBSTRAT COMPRENANT LEDIT ALLIAGE ET UTILISATIONS DE CE SUBSTRAT

Publication

EP 3356579 A1 20180808 (EN)

Application

EP 16778284 A 20160930

Priority

- EP 15187511 A 20150930
- EP 2016073427 W 20160930

Abstract (en)

[origin: EP3150744A1] The invention provides an electroplating bath for electrochemical deposition of a novel Cu-Sn-Zn-Pd alloy on a substrate. The novel alloy is characterized by exceptional corrosion resistance and the commonly used precious metal intermediate layer (e.g. a Pd-layer) between the substrate and the finishing layer is no longer necessary which allows a substantial reduction of the production costs of the plated substrates.

IPC 8 full level

C25D 3/58 (2006.01); **C23C 18/48** (2006.01); **C25D 3/60** (2006.01); **C25D 5/10** (2006.01); **C25D 7/00** (2006.01)

CPC (source: EP US)

C22C 9/02 (2013.01 - EP); **C25D 3/58** (2013.01 - EP US); **C25D 3/60** (2013.01 - EP); **C25D 5/10** (2013.01 - EP US); **C25D 5/611** (2020.08 - EP US); **C25D 5/627** (2020.08 - EP US); **C25D 7/005** (2013.01 - EP)

Citation (search report)

See references of WO 2017055553A1

Cited by

FR3118067A1; WO2022128608A1

Designated contracting state (EPC)

AL AT BE BG CH CY CZ DE DK EE ES FI FR GB GR HR HU IE IS IT LI LT LU LV MC MK MT NL NO PL PT RO RS SE SI SK SM TR

Designated extension state (EPC)

BA ME

DOCDB simple family (publication)

EP 3150744 A1 20170405; **EP 3150744 B1 20200212**; CN 108138346 A 20180608; CN 108138346 B 20210305; EP 3356579 A1 20180808; EP 3356579 B1 20200311; ES 2790583 T3 20201028; ES 2791197 T3 20201103; PT 3150744 T 20200512; PT 3356579 T 20200616; WO 2017055553 A1 20170406

DOCDB simple family (application)

EP 15187511 A 20150930; CN 201680056531 A 20160930; EP 16778284 A 20160930; EP 2016073427 W 20160930; ES 15187511 T 20150930; ES 16778284 T 20160930; PT 15187511 T 20150930; PT 16778284 T 20160930